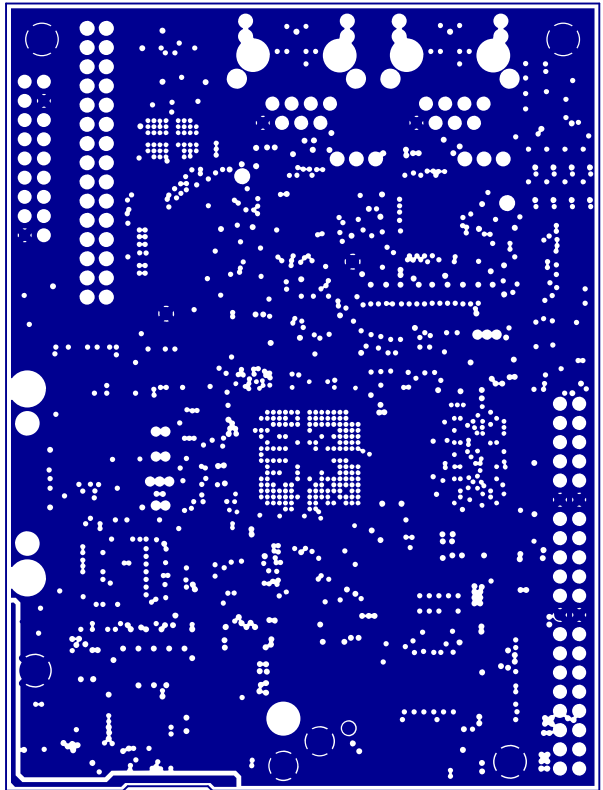


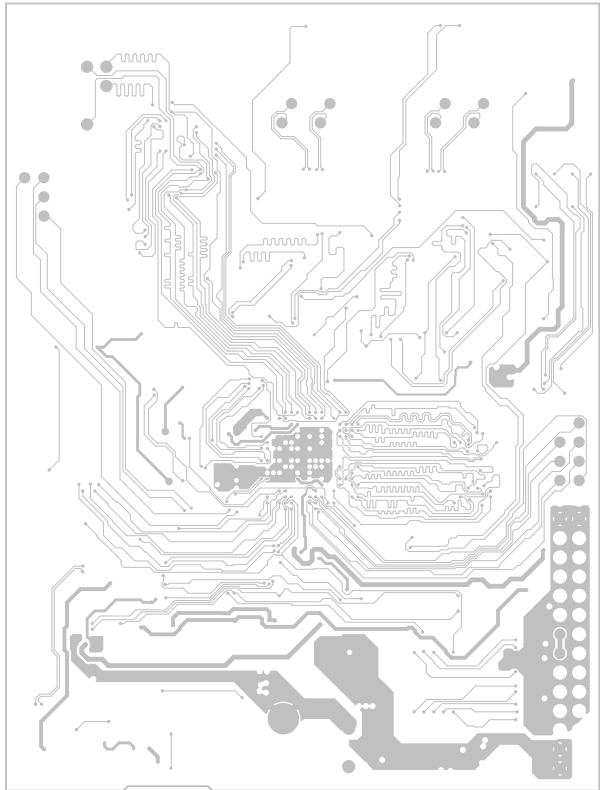
TIDEP0053

CUSTOMER NAME: TEXAS INSTRUMENTS			
BOARD NAME: ICE		DESCRIPTION: LAYER 1 - PRIMARY SIDE	
BOARD NO: 3H0013	REV: 2.1A	DATE: 04/18/2013	SH ₁ OF ₆



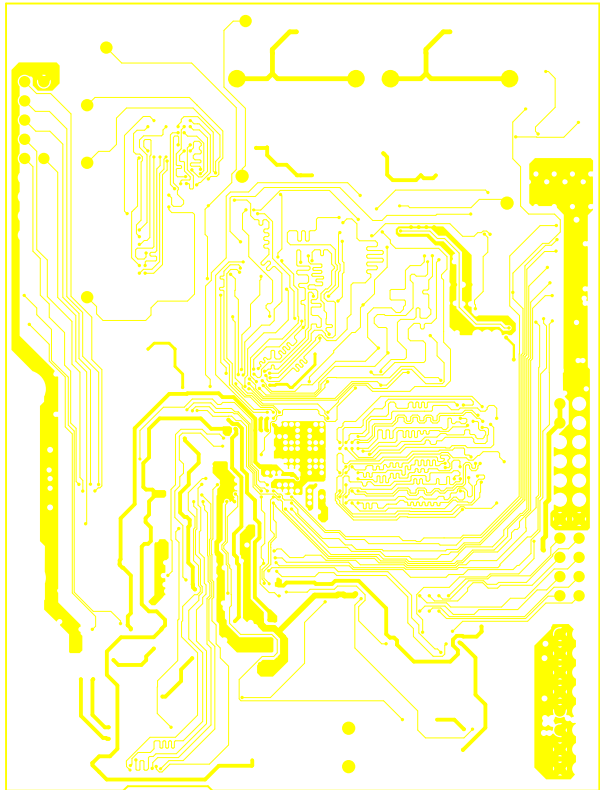
TIDEP0053

CUSTOMER NAME: TEXAS INSTRUMENTS			
BOARD NAME: ICE		DESCRIPTION: LAYER 2 - GROUND PLANE	
BOARD NO: 3H0013	REV: 2.1A	DATE: 04/18/2013	SH ₂ OF ₆



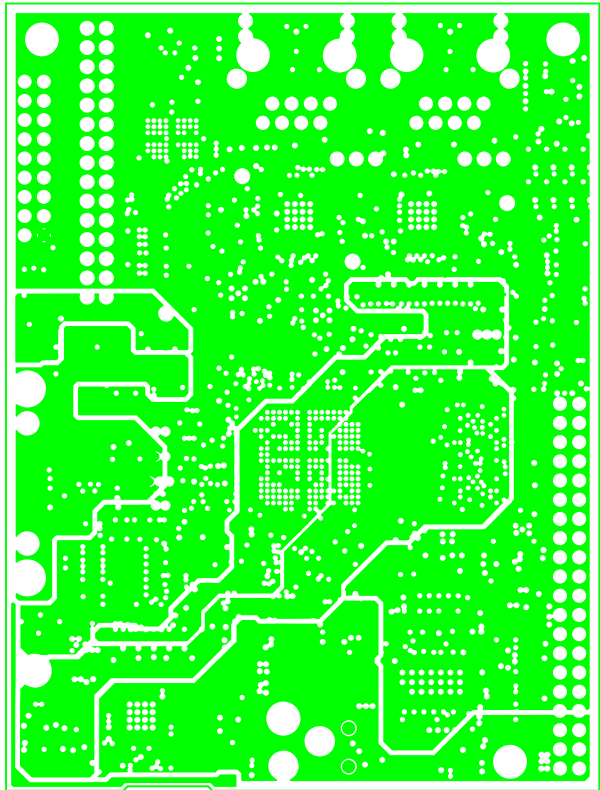
TIDEP0053

CUSTOMER NAME: TEXAS INSTRUMENTS			
BOARD NAME: ICE		DESCRIPTION: LAYER 3 - SIGNAL LAYER 1	
BOARD NO: 3H0013	REV: 2.1A	DATE: 04/18/2013	SH ₃ OF ₆



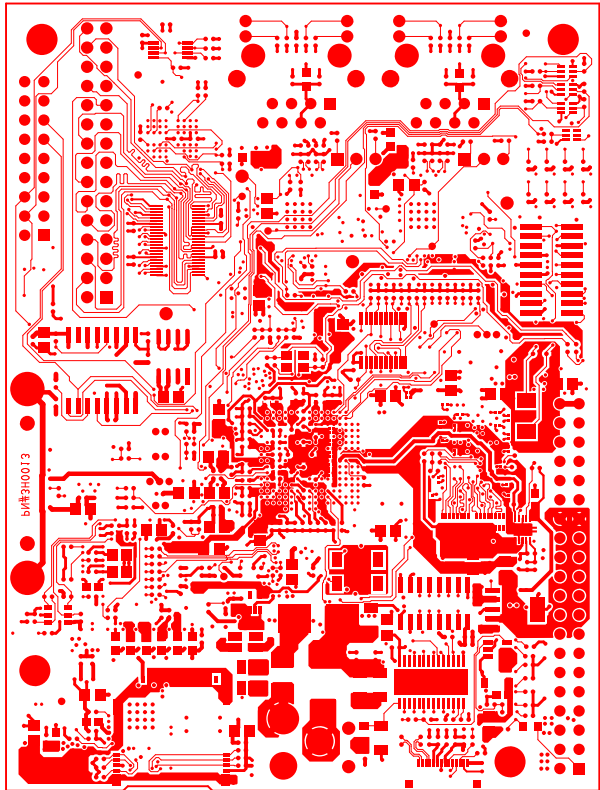
TIDEP0053

CUSTOMER NAME: TEXAS INSTRUMENTS			
BOARD NAME: ICE		DESCRIPTION: LAYER 4 - SIGNAL LAYER 2	
BOARD NO: 3H0013	REV: 2.1A	DATE: 04/18/2013	SH ₄ OF ₆



TIDEP0053

CUSTOMER NAME: TEXAS INSTRUMENTS			
BOARD NAME: ICE		DESCRIPTION: LAYER 5 - POWER LAYER	
BOARD NO: 3H0013	REV: 2.1A	DATE: 04/18/2013	SH ₅ OF ₆



TIDEP0053

CUSTOMER NAME: TEXAS INSTRUMENTS			
BOARD NAME: ICE		DESCRIPTION: LAYER 6 SECONDARY SIDE	
BOARD NO: 3H0013	REV: 2.1A	DATE: 04/18/2013	SH 6 OF 6

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